

after polishing the metal layer, introducing a second agent consisting of hydrogen peroxide to rinse the surface of the metal plug.

24. (New) A method of removing at least one particle from a surface of a metal plug disposed over a substrate comprising:

depositing a slurry onto a metal layer over the metal plug;

polishing the metal layer; and

after polishing the metal layer, rinsing the surface of the metal plug with a solution consisting of hydrogen peroxide.

25. (New) A method comprising:

polishing a metal layer over a conductive plug with a slurry;

after polishing the metal layer, introducing a rinsing solution onto the conductive plug, the rinsing solution consisting of hydrogen peroxide.

26. (New) A method of removing a particle from a surface of a metal plug formed in a via comprising:

introducing a first agent to a metal layer;

polishing the metal layer with the first agent; and

after polishing the metal layer, introducing a second agent consisting essentially of hydrogen peroxide to rinse the surface of the metal plug.

27. (New) A method of removing at least one particle from a surface of a metal plug disposed over a substrate comprising:

depositing a slurry onto a metal layer over the metal plug;

polishing the metal layer; and

after polishing the metal layer, rinsing the surface of the metal plug with a solution consisting essentially of hydrogen peroxide.

28. (New) A method comprising:

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comp polishing a metal layer over a conductive plug with a slurry;

after polishing the metal layer, introducing a rinsing solution onto the conductive plug, the rinsing solution consisting essentially of hydrogen peroxide.
